

## High Speed CMOS Logic Quad 2-Input EXCLUSIVE OR Gate

### Features

- **Typical Propagation Delay:** 9ns at  $V_{CC} = 5V$ ,  $C_L = 15pF$ ,  $T_A = 25^\circ C$
- **Fanout (Over Temperature Range)**
  - Standard Outputs . . . . . 10 LSTTL Loads
  - Bus Driver Outputs . . . . . 15 LSTTL Loads
- **Wide Operating Temperature Range . . . -55°C to 125°C**
- **Balanced Propagation Delay and Transition Times**
- **Significant Power Reduction Compared to LSTTL Logic ICs**
- **HC Types**
  - 2V to 6V Operation
  - High Noise Immunity:  $N_{IL} = 30\%$ ,  $N_{IH} = 30\%$  of  $V_{CC}$  at  $V_{CC} = 5V$
- **HCT Types**
  - 4.5V to 5.5V Operation
  - Direct LSTTL Input Logic Compatibility,  $V_{IL} = 0.8V$  (Max),  $V_{IH} = 2V$  (Min)
  - CMOS Input Compatibility,  $I_I \leq 1\mu A$  at  $V_{OL}$ ,  $V_{OH}$

### Applications

- Logical Comparators
- Parity Generators and Checkers
- Adders and Subtractors

### Description

The 'HC86 and 'HCT86 contain four independent EXCLUSIVE OR gates in one package. They provide the system designer with a means for implementation of the EXCLUSIVE OR function. Logic gates utilize silicon gate CMOS technology to achieve operating speeds similar to LSTTL gates with the low power consumption of standard CMOS integrated circuits. All devices have the ability to drive 10 LSTTL loads. The HCT logic family is functionally pin compatible with the standard LS logic family.

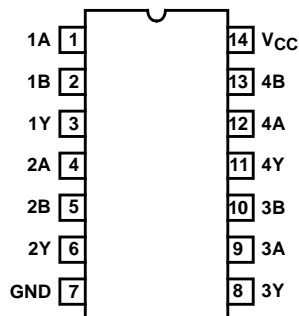
### Ordering Information

PART NUMBER	TEMP. RANGE (°C)	PACKAGE
CD54HC86F3A	-55 to 125	14 Ld CERDIP
CD54HCT86F3A	-55 to 125	14 Ld CERDIP
CD74HC86E	-55 to 125	14 Ld PDIP
CD74HC86M	-55 to 125	14 Ld SOIC
CD74HC86M96	-55 to 125	14 Ld SOIC
CD74HCT86E	-55 to 125	14 Ld PDIP
CD74HCT86M	-55 to 125	14 Ld SOIC
CD74HCT86M96	-55 to 125	14 Ld SOIC

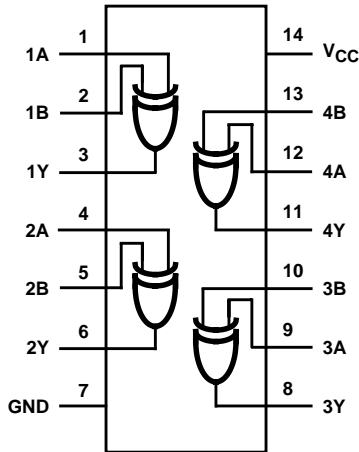
NOTE: When ordering, use the entire part number. The suffix 96 denotes tape and reel.

### Pinout

CD54HC86, CD54HCT86  
(CERDIP)  
CD74HC86, CD74HCT86  
(PDIP, SOIC)  
TOP VIEW



**Functional Diagram**

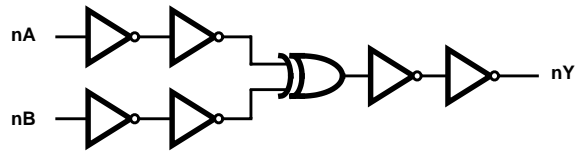


TRUTH TABLE

INPUTS		OUTPUT
nA	nB	nY
L	L	L
L	H	H
H	L	H
H	H	L

NOTE: H = High Voltage Level, L = Low Voltage Level

**Logic Symbol**



# CD54/74HC86, CD54/74HCT86

## Absolute Maximum Ratings

DC Supply Voltage, $V_{CC}$ .....	-0.5V to 7V
DC Input Diode Current, $I_{IK}$	
For $V_I < -0.5V$ or $V_I > V_{CC} + 0.5V$ .....	$\pm 20mA$
DC Output Diode Current, $I_{OK}$	
For $V_O < -0.5V$ or $V_O > V_{CC} + 0.5V$ .....	$\pm 20mA$
DC Output Source or Sink Current per Output Pin, $I_O$	
For $V_O > -0.5V$ or $V_O < V_{CC} + 0.5V$ .....	$\pm 25mA$
DC $V_{CC}$ or Ground Current, $I_{CC}$ or $I_{GND}$ .....	$\pm 50mA$

## Thermal Information

Thermal Resistance (Typical, Note 1)	$\theta_{JA}$ (°C/W)
PDIP Package .....	80
SOIC Package .....	86
Maximum Junction Temperature .....	150°C
Maximum Storage Temperature Range .....	-65°C to 150°C
Maximum Lead Temperature (Soldering 10s) .....	300°C (SOIC - Lead Tips Only)

## Operating Conditions

Temperature Range ( $T_A$ ) .....	-55°C to 125°C
Supply Voltage Range, $V_{CC}$	
HC Types .....	.2V to 6V
HCT Types .....	4.5V to 5.5V
DC Input or Output Voltage, $V_I, V_O$ .....	0V to $V_{CC}$
Input Rise and Fall Time	
2V .....	1000ns (Max)
4.5V .....	500ns (Max)
6V .....	400ns (Max)

CAUTION: Stresses above those listed in "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress only rating and operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied.

### NOTE:

- The package thermal impedance is calculated in accordance with JESD 51-7.

## DC Electrical Specifications

PARAMETER	SYMBOL	TEST CONDITIONS		$V_{CC}$ (V)	25°C			-40°C TO +85°C		-55°C TO 125°C		UNITS
		$V_I$ (V)	$I_O$ (mA)		MIN	TYP	MAX	MIN	MAX	MIN	MAX	
<b>HC TYPES</b>												
High Level Input Voltage	$V_{IH}$	-	-	2	1.5	-	-	1.5	-	1.5	-	V
				4.5	3.15	-	-	3.15	-	3.15	-	V
				6	4.2	-	-	4.2	-	4.2	-	V
Low Level Input Voltage	$V_{IL}$	-	-	2	-	-	0.5	-	0.5	-	0.5	V
				4.5	-	-	1.35	-	1.35	-	1.35	V
				6	-	-	1.8	-	1.8	-	1.8	V
High Level Output Voltage CMOS Loads	$V_{OH}$	$V_{IH}$ or $V_{IL}$	-0.02	2	1.9	-	-	1.9	-	1.9	-	V
			-0.02	4.5	4.4	-	-	4.4	-	4.4	-	V
			-0.02	6	5.9	-	-	5.9	-	5.9	-	V
High Level Output Voltage TTL Loads			-4	4.5	3.98	-	-	3.84	-	3.7	-	V
			-5.2	6	5.48	-	-	5.34	-	5.2	-	V
Low Level Output Voltage CMOS Loads	$V_{OL}$	$V_{IH}$ or $V_{IL}$	0.02	2	-	-	0.1	-	0.1	-	0.1	V
			0.02	4.5	-	-	0.1	-	0.1	-	0.1	V
			0.02	6	-	-	0.1	-	0.1	-	0.1	V
Low Level Output Voltage TTL Loads			4	4.5	-	-	0.26	-	0.33	-	0.4	V
			5.2	6	-	-	0.26	-	0.33	-	0.4	V
Input Leakage Current	$I_I$	$V_{CC}$ or GND	-	6	-	-	$\pm 0.1$	-	$\pm 1$	-	$\pm 1$	$\mu A$
Quiescent Device Current	$I_{CC}$	$V_{CC}$ or GND	0	6	-	-	2	-	20	-	40	$\mu A$

## CD54/74HC86, CD54/74HCT86

### DC Electrical Specifications (Continued)

PARAMETER	SYMBOL	TEST CONDITIONS		V <sub>CC</sub> (V)	25°C			-40°C TO +85°C		-55°C TO 125°C		UNITS
		V <sub>I</sub> (V)	I <sub>O</sub> (mA)		MIN	TYP	MAX	MIN	MAX	MIN	MAX	
<b>HCT TYPES</b>												
High Level Input Voltage	V <sub>IH</sub>	-	-	4.5 to 5.5	2	-	-	2	-	2	-	V
Low Level Input Voltage	V <sub>IL</sub>	-	-	4.5 to 5.5	-	-	0.8	-	0.8	-	0.8	V
High Level Output Voltage CMOS Loads	V <sub>OH</sub>	V <sub>IH</sub> or V <sub>IL</sub>	-0.02	4.5	4.4	-	-	4.4	-	4.4	-	V
High Level Output Voltage TTL Loads			-4	4.5	3.98	-	-	3.84	-	3.7	-	V
Low Level Output Voltage CMOS Loads	V <sub>OL</sub>	V <sub>IH</sub> or V <sub>IL</sub>	0.02	4.5	-	-	0.1	-	0.1	-	0.1	V
Low Level Output Voltage TTL Loads			4	4.5	-	-	0.26	-	0.33	-	0.4	V
Input Leakage Current	I <sub>I</sub>	V <sub>CC</sub> and GND	-	5.5	-		±0.1	-	±1	-	±1	μA
Quiescent Device Current	I <sub>CC</sub>	V <sub>CC</sub> or GND	0	5.5	-	-	2	-	20	-	40	μA
Additional Quiescent Device Current Per Input Pin: 1 Unit Load (Note 2)	ΔI <sub>CC</sub>	V <sub>CC</sub> - 2.1	-	4.5 to 5.5	-	100	360	-	450	-	490	μA

NOTE:

- For dual-supply systems theoretical worst case (V<sub>I</sub> = 2.4V, V<sub>CC</sub> = 5.5V) specification is 1.8mA.

### HCT Input Loading Table

INPUT	UNIT LOADS
All	1

NOTE: Unit Load is ΔI<sub>CC</sub> limit specified in DC Electrical Specifications table, e.g. 360μA max at 25°C.

### Switching Specifications Input t<sub>r</sub>, t<sub>f</sub> = 6ns

PARAMETER	SYMBOL	TEST CONDITIONS	V <sub>CC</sub> (V)	25°C			-40°C TO 85°C		-55°C TO 125°C		UNITS
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
<b>HC TYPES</b>											
Propagation Delay, Input to Output (Figure 1)	t <sub>PLH</sub> , t <sub>PHL</sub>	C <sub>L</sub> = 50pF	2	-	-	120	-	150	-	180	ns
			4.5	-	-	24	-	30	-	36	ns
			6	-	-	20	-	26	-	31	ns
Propagation Delay, Data Input to Output Y	t <sub>PLH</sub> , t <sub>PHL</sub>	C <sub>L</sub> = 15pF	5	-	9	-	-	-	-	ns	
Transition Times (Figure 1)	t <sub>TLH</sub> , t <sub>THL</sub>	C <sub>L</sub> = 50pF	2	-	-	75	-	95	-	110	ns
			4.5	-	-	15	-	19	-	22	ns
			6	-	-	13	-	16	-	19	ns

## CD54/74HC86, CD54/74HCT86

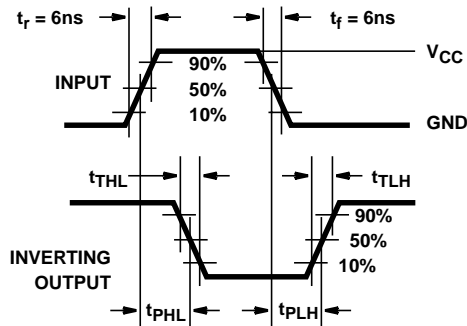
### Switching Specifications Input $t_r$ , $t_f$ = 6ns (Continued)

PARAMETER	SYMBOL	TEST CONDITIONS	$V_{CC}$ (V)	25°C			-40°C TO 85°C		-55°C TO 125°C		UNITS
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
Input Capacitance	$C_I$	-	-	-	-	10	-	10	-	10	pF
Power Dissipation Capacitance (Notes 3, 4)	$C_{PD}$	-	5	-	22	-	-	-	-	-	pF
<b>HCT TYPES</b>											
Propagation Delay, Input to Output (Figure 2)	$t_{PLH}$ , $t_{PHL}$	$C_L = 50\text{pF}$	4.5	-	-	32	-	40	-	48	ns
Propagation Delay, Data Input to Output Y	$t_{PLH}$ , $t_{PHL}$	$C_L = 15\text{pF}$	5	-	13	-	-	-	-	-	ns
Transition Times (Figure 2)	$t_{TLH}$ , $t_{THL}$	$C_L = 50\text{pF}$	4.5	-	-	15	-	19	-	22	ns
Input Capacitance	$C_I$	-	-	-	-	10	-	10	-	10	pF
Power Dissipation Capacitance (Notes 3, 4)	$C_{PD}$	-	5	-	27	-	-	-	-	-	pF

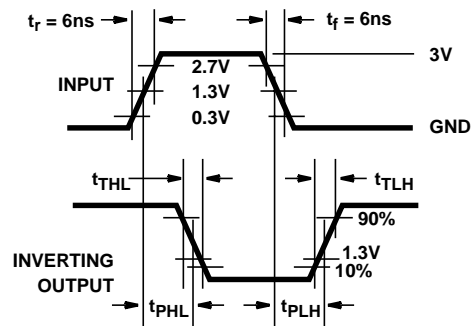
**NOTES:**

3.  $C_{PD}$  is used to determine the dynamic power consumption, per gate.
4.  $P_D = V_{CC}^2 f_i (C_{PD} + C_L)$  where  $f_i$  = input frequency,  $C_L$  = output load capacitance,  $V_{CC}$  = supply voltage.

### Test Circuits and Waveforms



**FIGURE 1. HC AND HCU TRANSITION TIMES AND PROPAGATION DELAY TIMES, COMBINATION LOGIC**

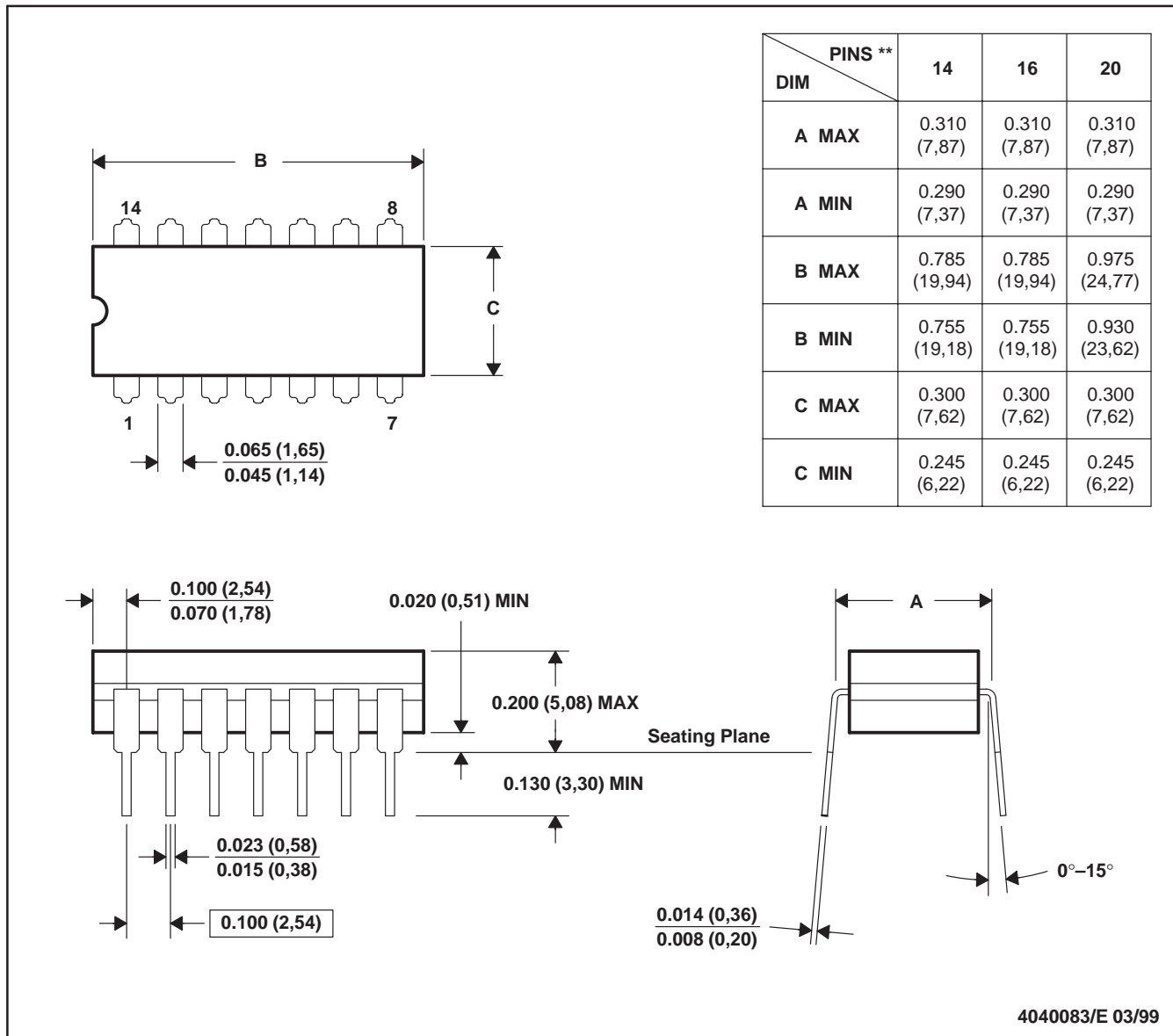


**FIGURE 2. HCT TRANSITION TIMES AND PROPAGATION DELAY TIMES, COMBINATION LOGIC**

J (R-GDIP-T\*\*)

CERAMIC DUAL-IN-LINE

14 LEADS SHOWN

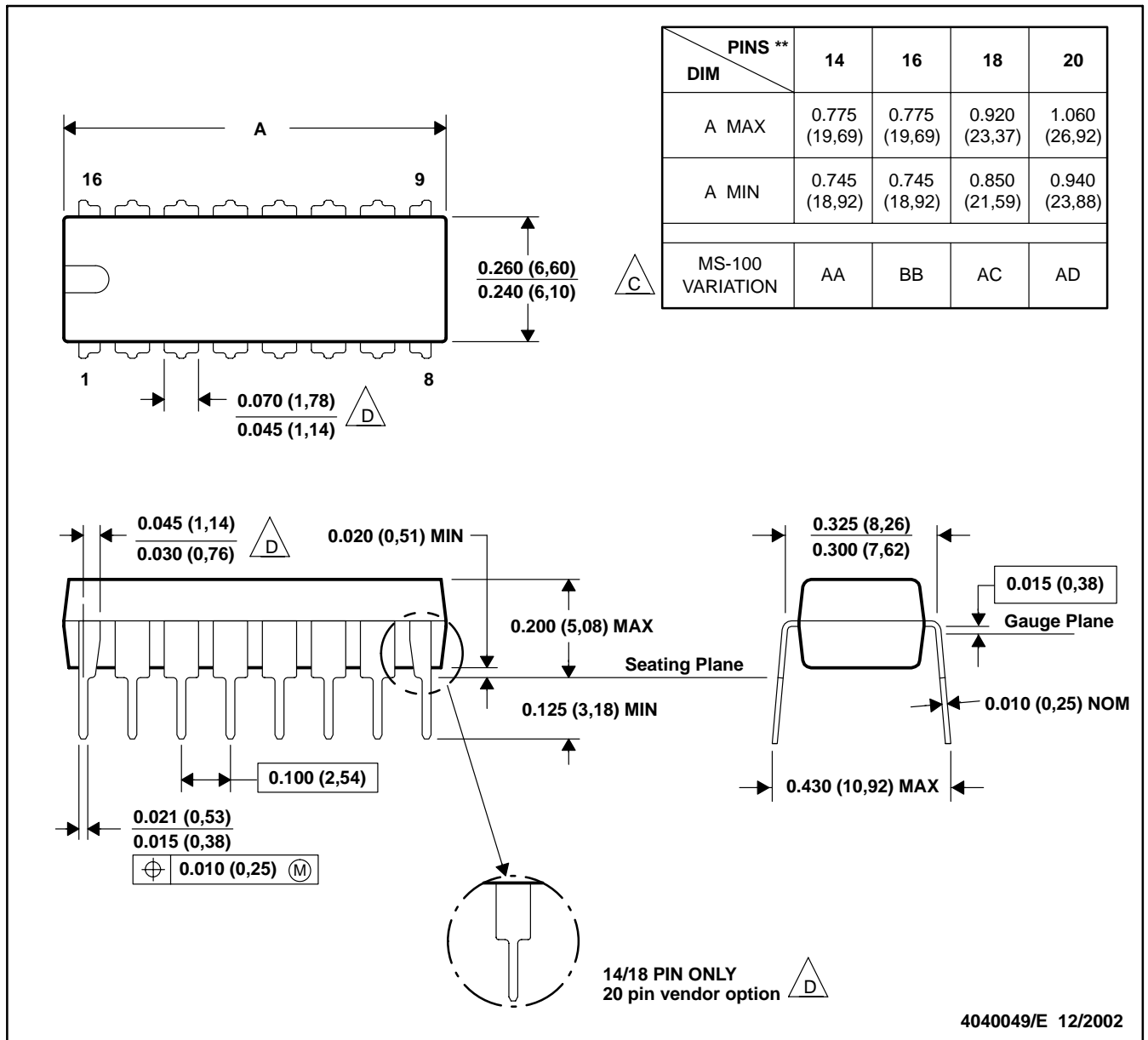


- NOTES: A. All linear dimensions are in inches (millimeters).  
 B. This drawing is subject to change without notice.  
 C. This package is hermetically sealed with a ceramic lid using glass frit.  
 D. Index point is provided on cap for terminal identification.  
 E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, and GDIP1-T20

N (R-PDIP-T\*\*)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- NOTES: A. All linear dimensions are in inches (millimeters).  
 B. This drawing is subject to change without notice.  
 C Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).  
 D The 20 pin end lead shoulder width is a vendor option, either half or full width.

4040049/E 12/2002

D (R-PDSO-G\*\*)

PLASTIC SMALL-OUTLINE PACKAGE

8 PINS SHOWN



4040047/E 09/01

- NOTES: A. All linear dimensions are in inches (millimeters).  
 B. This drawing is subject to change without notice.  
 C. Body dimensions do not include mold flash or protrusion, not to exceed 0.006 (0,15).  
 D. Falls within JEDEC MS-012



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